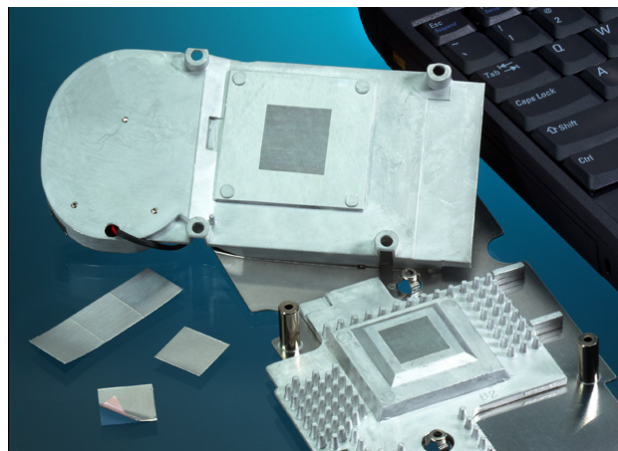


### High Performance, Reworkable Phase Change Material

#### DESCRIPTION

Chomerics' patent pending THERMFLOW™ T766 phase change thermal interface material is recommended for applications where rework is important. The material provides the high performance properties of typical phase change materials with the added benefit of easy removal. It consists of a tacky, electrically non-conductive phase change film on one side of a conformable metal foil carrier. T766 can be assembled onto a heat sink or heat spreader, leaving the metal foil exposed. The natural tack of the phase change polymer holds the T766 to the heat sink while the foil layer acts as a highly conductive interface between the component and heat sink and allows a clean break during disassembly. The foil also eliminates the need for a protective liner, which simplifies the final assembly process and minimizes shipping and contamination concerns.

Chomerics is now offering T766 in two thicknesses, 0.0035 inches and 0.006 inches. This added thickness option allows designers more flexibility in specifying interface material.



	Typical Properties	T766		Test Method
CONSTRUCTION	Carrier	Conformable Metal		---
	Color (Polymer/Metal)	Light Gray/Silver		Visual
	Carrier Thickness, inch (mm)	0.001 (0.025)		ASTM D374
	Polymer Thickness, inch (mm)	0.0025 (0.064)	0.005 (0.127)	ASTM D374
	Overall Thickness, inch (mm)	0.0035 (0.089)	0.006 (0.15)	ASTM D374
THERMAL	Thermal Impedance, °C-in <sup>2</sup> /W @ 70°C, 50 psi	0.04		ASTM D5470 modified
	Apparent Thermal Conductivity, W/m-K	Polymer 0.7		ASTM D5470 modified
		Carrier 75		
	Phase Change Temperature Range, °C	51-58		ASTM D3418
Operating Temperature Range, °C	-60 to +125		---	
MECH	Specific Gravity	3.0		ASTM D792

#### FEATURES

- Conformable metal foil carrier allows for a clean break during heat sink disassembly
- There are no additional liners to protect the phase change material once it is assembled to the heat sink
- Offered in two thicknesses to accommodate a range of applications

#### APPLICATION

THERMFLOW T766 material is inherently tacky on the light gray polymer film side for easy attachment to the heat sink or thermal spreader. The metal foil side of the material is left exposed for contact with the electronic component to be cooled. The dry nature of the foil side enables easy removal of the heat sink for rework on the assembly. T766 pads are supplied kiss-cut on rolls for easy installation.

If rework is needed, the T766 pads can be removed from the heat sink at the light gray polymer interface using a single-edged razor, and then cleaning the heat sink surface with isopropanol (IPA) solvent.